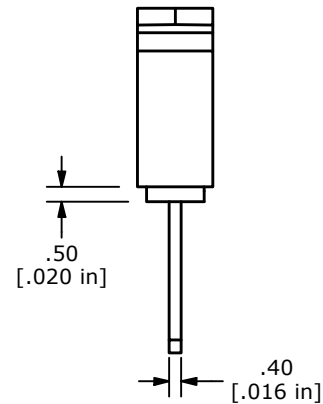
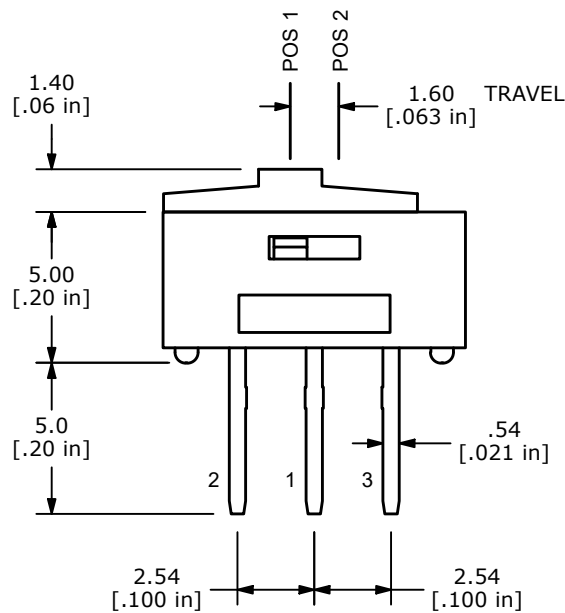
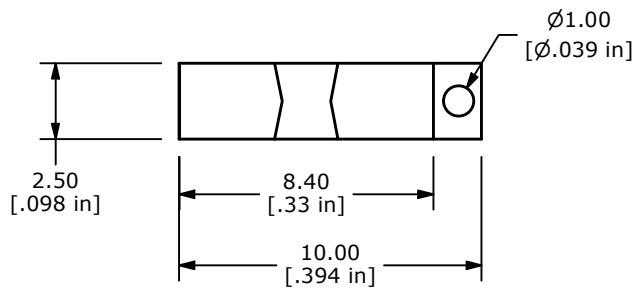
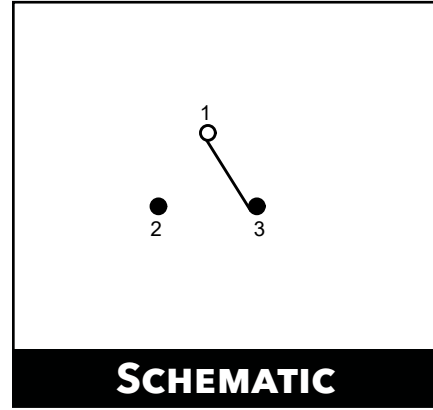
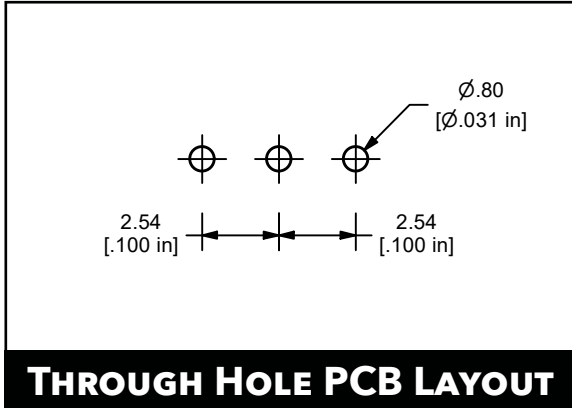




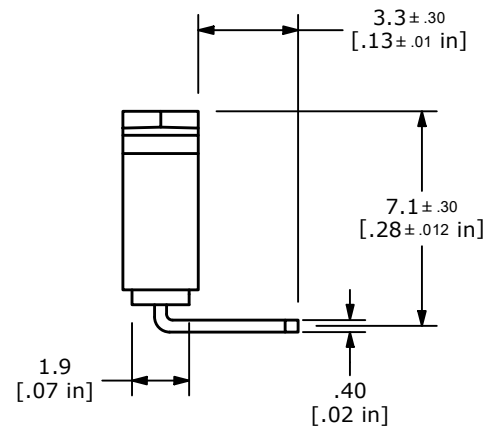
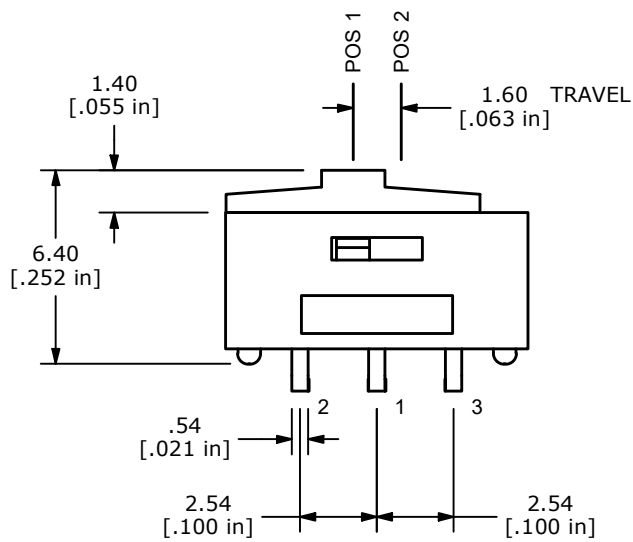
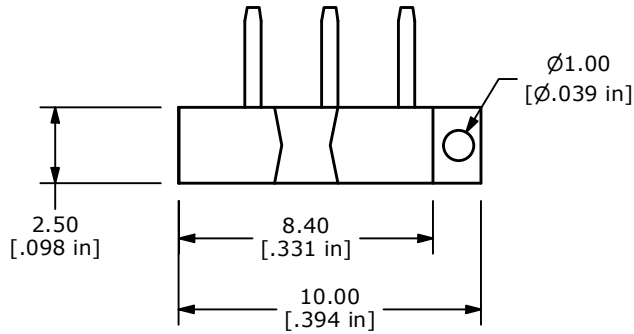
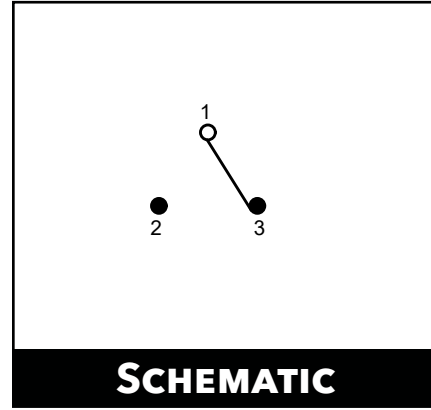
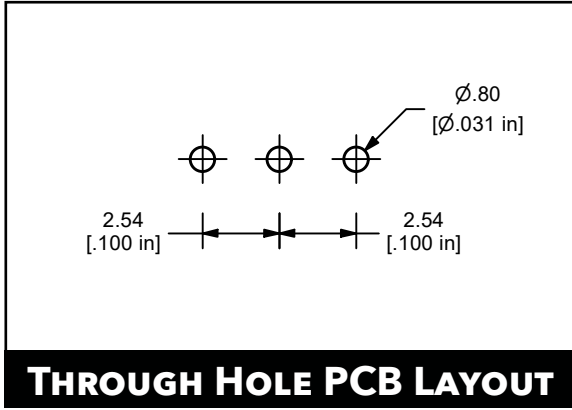
EGJ1210 SERIES SLIDE SWITCH

BODY DIMENSIONS



EGJ1210 SERIES SLIDE SWITCH

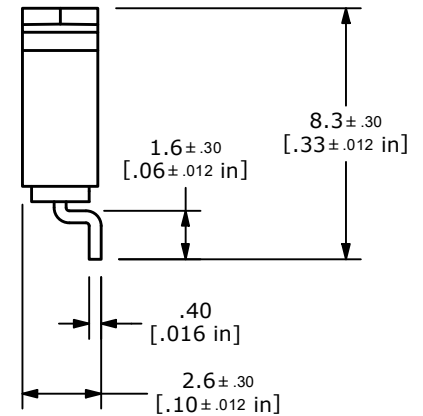
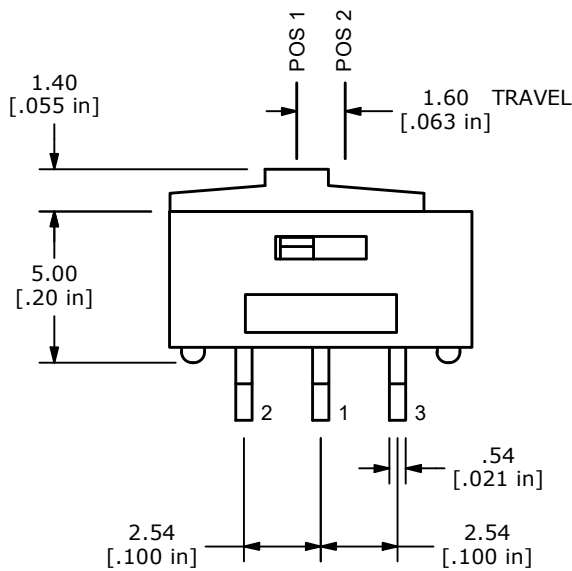
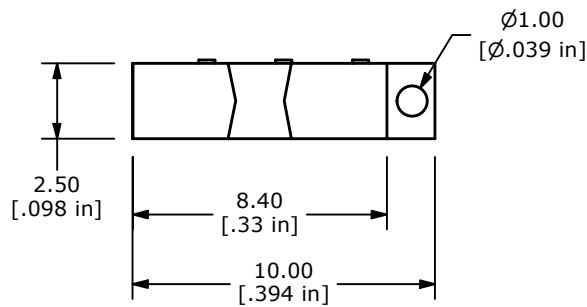
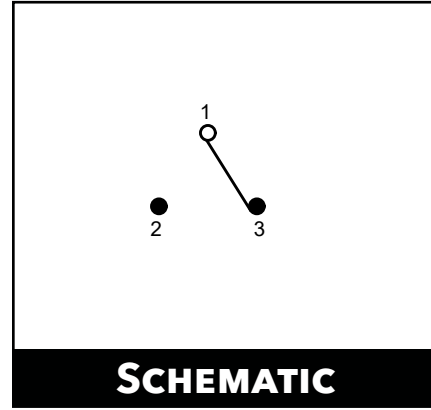
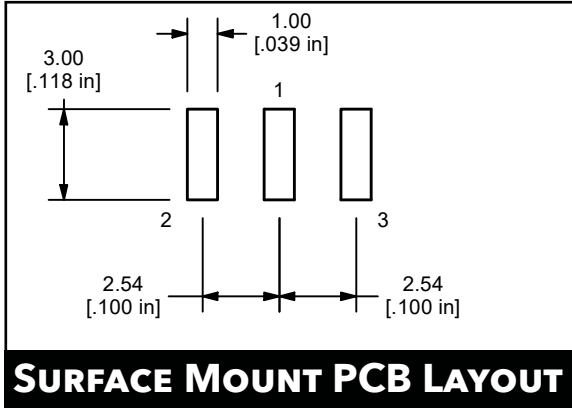
BODY DIMENSIONS





EGJ1210 SERIES SLIDE SWITCH

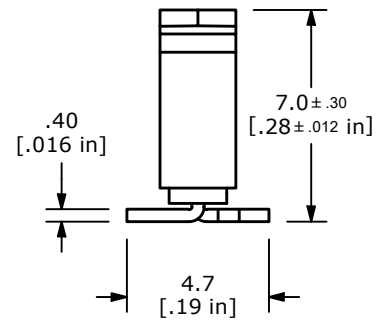
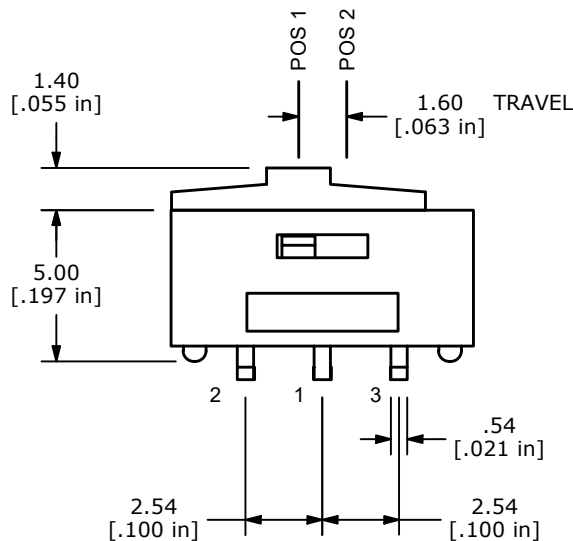
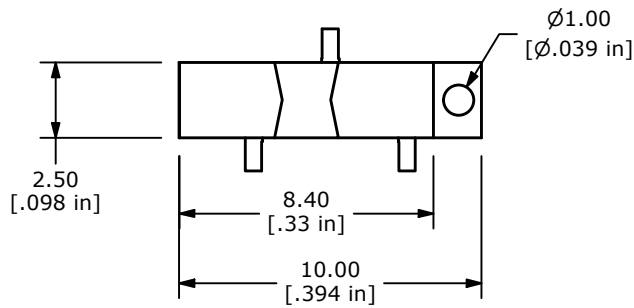
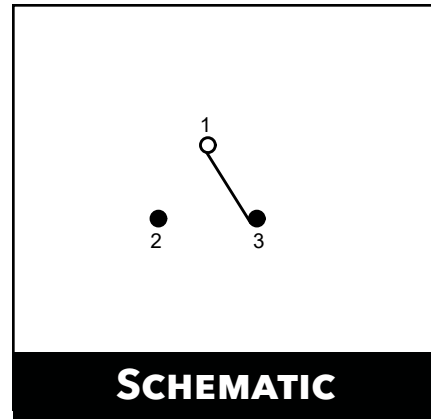
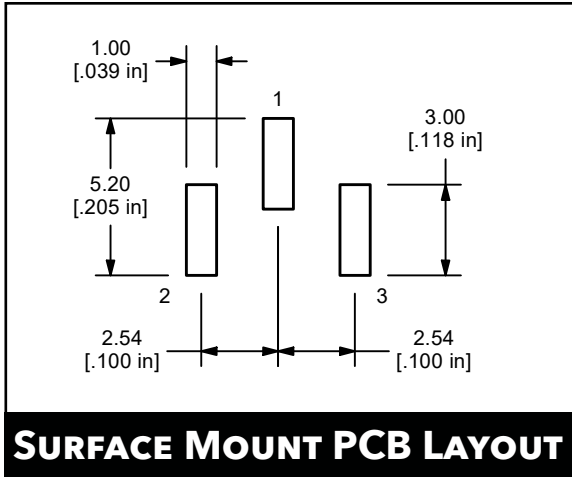
BODY DIMENSIONS





EGJ1210 SERIES SLIDE SWITCH

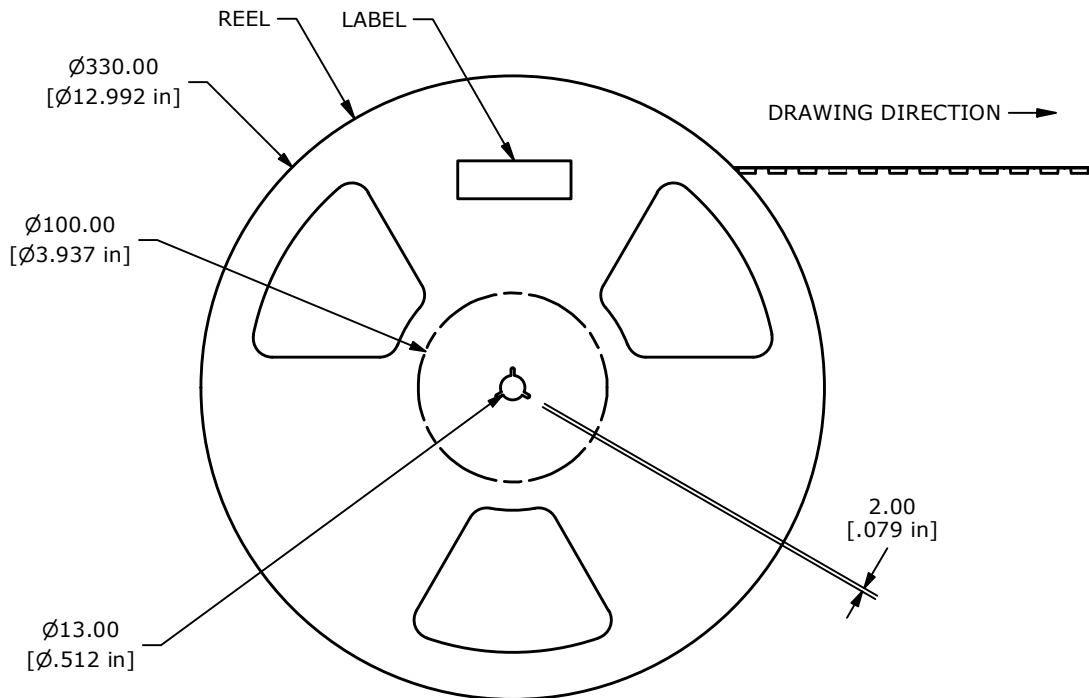
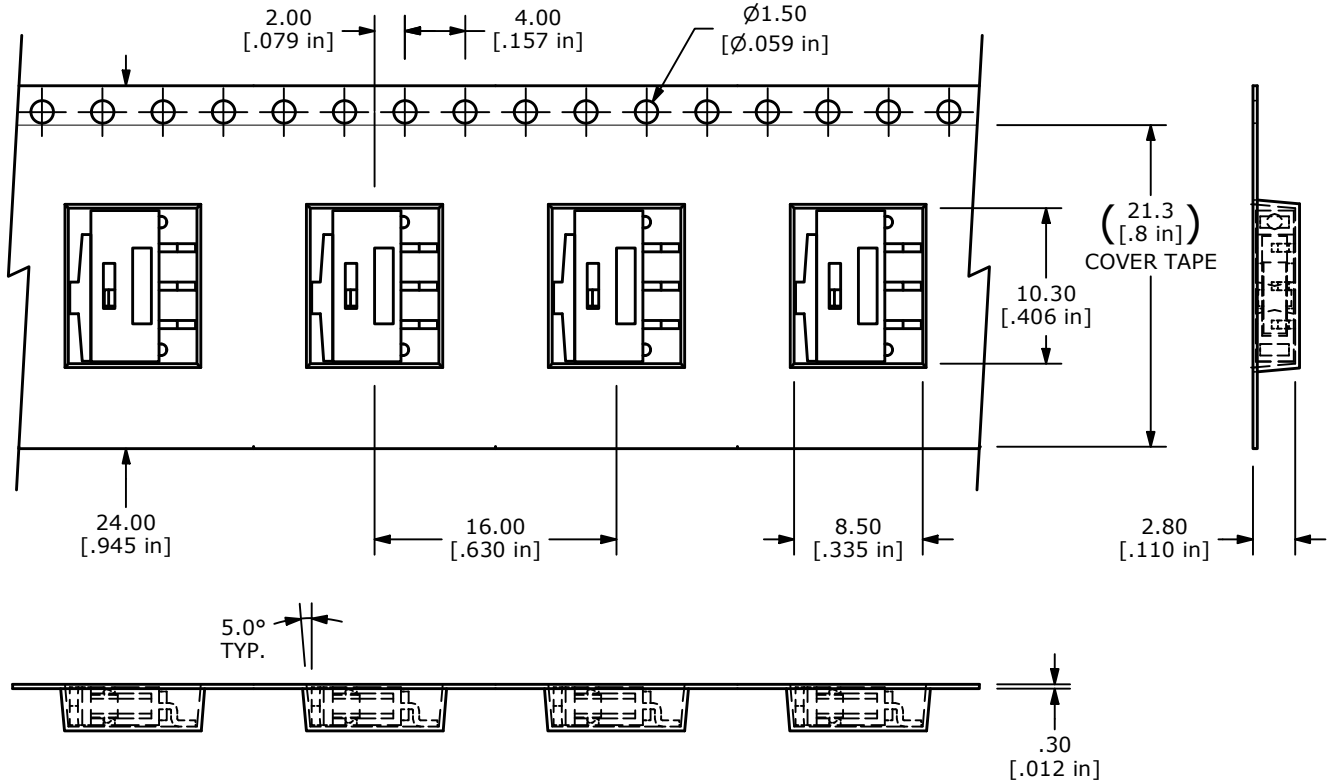
BODY DIMENSIONS





EGJ1210 SERIES SLIDE SWITCH

BODY DIMENSIONS TAPE AND REEL



EGJ1210 SERIES SLIDE SWITCH

RECOMMENDED SOLDER PROCESS

Most contamination problems can be prevented by exercising care during the cleaning and soldering process. Care should be taken not to immerse or spray unsealed switches during flux removal. Contact E-Switch for specific soldering recommendations and specifications not shown. Generalized soldering procedures are outlined below.

“TYPICAL” SMT REFLOW (Pb and Pb-Free)

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate (T _{smax} to T _p)	3 °C/second max.	3 °C/second max.
Preheat		
-Temperature Min (T _{smin})	100 °C	150 °C
-Temperature Max (T _{smax})	150 °C	200 °C
-Time (t _{smin} to t _{smax})	60-120 seconds	60-180 seconds
Time Maintained above:		
-Temperature (T _L)	183 °C	217 °C
-Time (t _L)	60-150 seconds	60-150 seconds
Time within 5 °C of actual Peak Temperature (t _p)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6 °C/second max.	6 °C/second max.
Time 25 °C to Peak Temperature	6 minutes max.	8 minutes max.

Note 1: All temperatures refer to topside of the package, measured on the package surface.

